

# 74LVC1G17-Q100

## Single Schmitt trigger buffer

Rev. 1 — 9 July 2012

Product data sheet

## 1. General description

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The 74LVC1G17-Q100 provides a buffer function with Schmitt trigger input. It is capable of transforming slowly changing input signals into sharply defined outputs.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pf, R = 0  $\Omega$ )
- $\pm 24\text{ mA}$  output drive ( $V_{CC} = 3.0\text{ V}$ )
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Unlimited rise and fall times
- Inputs accept voltages up to 5 V
- Multiple package options



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVC1G17GW-Q100	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G17GV-Q100	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753

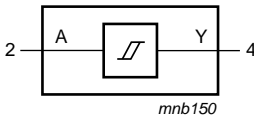
### 4. Marking

Table 2. Marking codes

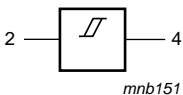
Type number	Marking <sup>[1]</sup>
74LVC1G17GW-Q100	VJ
74LVC1G17GV-Q100	V17

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

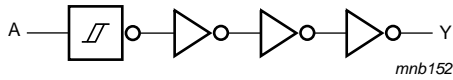
### 5. Functional diagram



**Fig 1. Logic symbol**



**Fig 2. IEC logic symbol**



**Fig 3. Logic diagram**

## 6. Pinning information

### 6.1 Pinning

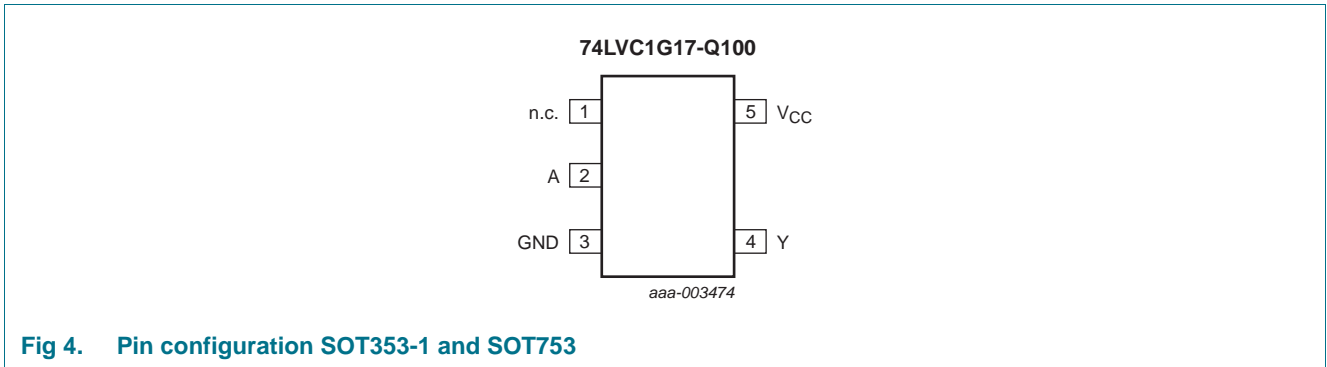


Fig 4. Pin configuration SOT353-1 and SOT753

### 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A	2	data input
GND	3	ground (0 V)
Y	4	data output
V <sub>CC</sub>	5	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input	Output
A	Y
L	L
H	H

[1] H = HIGH voltage level; L = LOW voltage level

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		[1] -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	$\pm 50$	mA
$V_O$	output voltage	Active mode	[1][2] -0.5	$V_{CC} + 0.5$	V
		Power-down mode	[1][2] -0.5	+6.5	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	250	mW
$T_{stg}$	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	Active mode	0	-	$V_{CC}$	V
		$V_{CC} = 0$ V; Power-down mode	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
<b><math>T_{amb} = -40</math> °C to +85 °C</b>						
$V_{OH}$	HIGH-level output voltage	$V_I = V_{T+}$ or $V_{T-}$				
		$I_O = -100$ $\mu$ A; $V_{CC} = 1.65$ V to 5.5 V	$V_{CC} - 0.1$	-	-	V
		$I_O = -4$ mA; $V_{CC} = 1.65$ V	1.2	-	-	V
		$I_O = -8$ mA; $V_{CC} = 2.3$ V	1.9	-	-	V
		$I_O = -12$ mA; $V_{CC} = 2.7$ V	2.2	-	-	V
		$I_O = -24$ mA; $V_{CC} = 3.0$ V	2.3	-	-	V
		$I_O = -32$ mA; $V_{CC} = 4.5$ V	3.8	-	-	V

**Table 7. Static characteristics ...continued**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V	-	-	0.1	V
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	-	0.45	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V	-	-	0.3	V
		I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	-	0.4	V
		I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V	-	-	0.55	V
		I <sub>O</sub> = 32 mA; V <sub>CC</sub> = 4.5 V	-	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	±0.1	±5	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 0 V	-	±0.1	±10	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 1.65 V to 5.5 V; I <sub>O</sub> = 0 A	-	0.1	10	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 5.5 V; per pin	-	5	500	μA
C <sub>I</sub>	input capacitance		-	5	-	pF
<b>T<sub>amb</sub> = -40 °C to +125 °C</b>						
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -4 mA; V <sub>CC</sub> = 1.65 V	0.95	-	-	V
		I <sub>O</sub> = -8 mA; V <sub>CC</sub> = 2.3 V	1.7	-	-	V
		I <sub>O</sub> = -12 mA; V <sub>CC</sub> = 2.7 V	1.9	-	-	V
		I <sub>O</sub> = -24 mA; V <sub>CC</sub> = 3.0 V	2.0	-	-	V
		I <sub>O</sub> = -32 mA; V <sub>CC</sub> = 4.5 V	3.4	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 100 μA; V <sub>CC</sub> = 1.65 V to 5.5 V	-	-	0.1	V
		I <sub>O</sub> = 4 mA; V <sub>CC</sub> = 1.65 V	-	-	0.7	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	-	0.6	V
		I <sub>O</sub> = 24 mA; V <sub>CC</sub> = 3.0 V	-	-	0.80	V
		I <sub>O</sub> = 32 mA; V <sub>CC</sub> = 4.5 V	-	-	0.80	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	±100	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 0 V	-	-	±200	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 1.65 V to 5.5 V; I <sub>O</sub> = 0 A	-	-	200	μA
ΔI <sub>CC</sub>	additional supply current	per pin; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 2.3 V to 5.5 V	-	-	5000	μA

[1] All typical values are measured at maximum V<sub>CC</sub> and T<sub>amb</sub> = 25 °C.

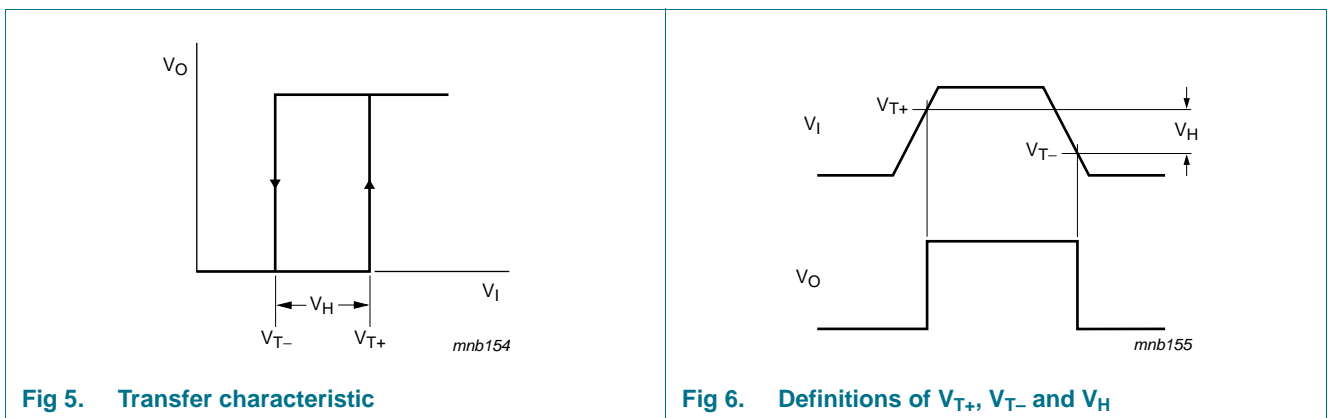
**Table 8. Transfer characteristics**

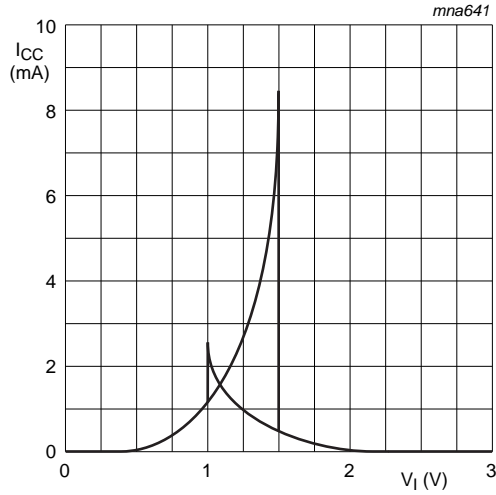
At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 5</a> and <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 1.8 V	0.82	1.0	1.14	0.79	1.14	V
		V <sub>CC</sub> = 2.3 V	1.03	1.2	1.40	1.00	1.40	V
		V <sub>CC</sub> = 3.0 V	1.29	1.5	1.71	1.26	1.71	V
		V <sub>CC</sub> = 4.5 V	1.84	2.1	2.36	1.81	2.36	V
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 5</a> and <a href="#">Figure 6</a>						
		V <sub>CC</sub> = 1.8 V	0.46	0.6	0.75	0.46	0.78	V
		V <sub>CC</sub> = 2.3 V	0.65	0.8	0.96	0.65	0.99	V
		V <sub>CC</sub> = 3.0 V	0.88	1.0	1.24	0.88	1.27	V
		V <sub>CC</sub> = 4.5 V	1.32	1.5	1.84	1.32	1.87	V
V <sub>H</sub>	hysteresis voltage	see <a href="#">Figure 5</a> , <a href="#">Figure 6</a> and <a href="#">Figure 7</a>						
		V <sub>CC</sub> = 1.8 V	0.26	0.4	0.51	0.19	0.51	V
		V <sub>CC</sub> = 2.3 V	0.28	0.4	0.57	0.22	0.57	V
		V <sub>CC</sub> = 3.0 V	0.31	0.5	0.64	0.25	0.64	V
		V <sub>CC</sub> = 4.5 V	0.40	0.6	0.77	0.34	0.77	V
		V <sub>CC</sub> = 5.5 V	0.47	0.6	0.88	0.41	0.88	V

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.

10.1 Transfer characteristic waveforms





V<sub>CC</sub> = 3.0 V

Fig 7. Typical transfer characteristics

## 11. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 9.

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	A to Y; see Figure 8 <sup>[2]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	4.1	11.0	1.0	14.0	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7	2.8	6.5	0.7	8.5	ns
		V <sub>CC</sub> = 2.7 V	0.7	3.2	6.5	0.7	8.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.7	3.0	5.5	0.7	7.0	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7	2.2	5.0	0.7	6.5	ns
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 3.3 V <sup>[3]</sup>	-	16.6	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

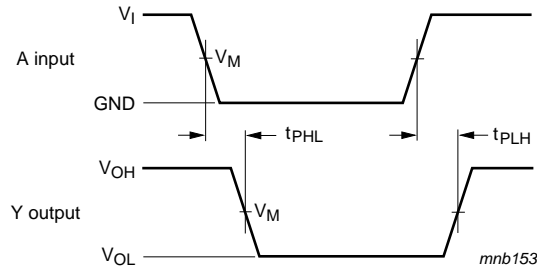
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

12. Waveforms

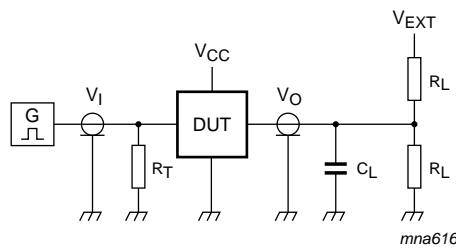


Measurement points are given in [Table 10](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 8. The input A to output Y propagation delay times**

**Table 10. Measurement points**

Supply voltage	Input	Output
$V_{CC}$	$V_M$	$V_M$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$



Test data is given in [Table 11](#).  
 Definitions for test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.  
 $V_{EXT}$  = External voltage for measuring switching times.

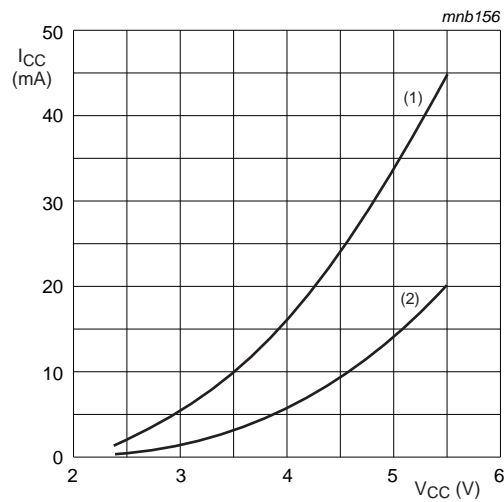
**Fig 9. Test circuit for measuring switching times**



Table 11. Test data

Supply voltage	Input		Load		V <sub>EXT</sub>
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>	C <sub>L</sub>	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>
1.65 V to 1.95 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V <sub>CC</sub>	≤ 2.5 ns	50 pF	500 Ω	open

### 13. Application information



Linear change of V<sub>I</sub> between 0.8 V to 2.0 V.

- (1) Positive-going edge.
- (2) Negative-going edge.

Fig 10. Average supply current as a function of supply voltage

14. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



Fig 11. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

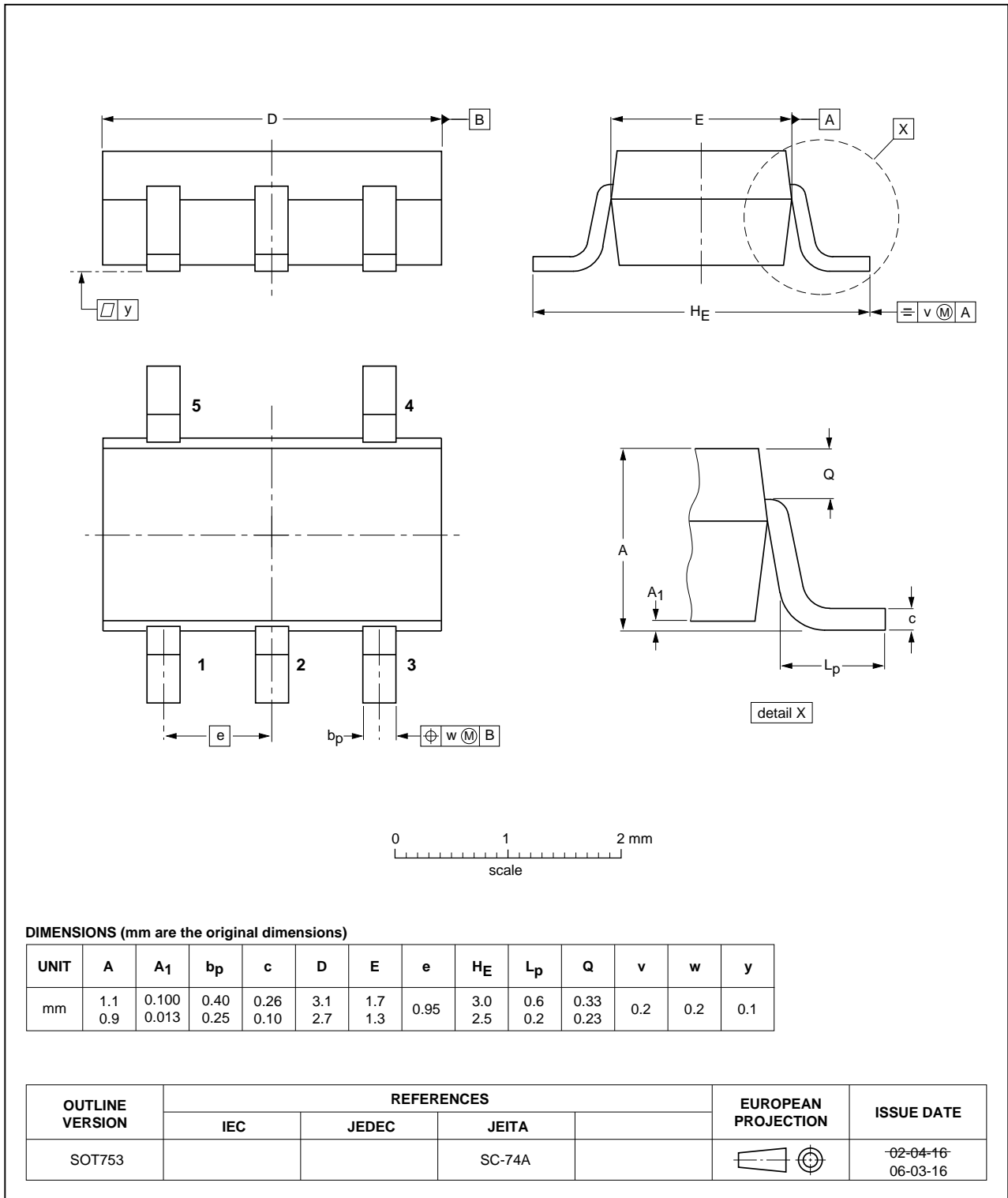


Fig 12. Package outline SOT753 (SC-74A)

## 15. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
TTL	Transistor-Transistor Logic
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
DUT	Device Under Test
MIL	Military

## 16. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G17_Q100 v.1	20120709	Product data sheet	-	-

## 17. Legal information

### 17.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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